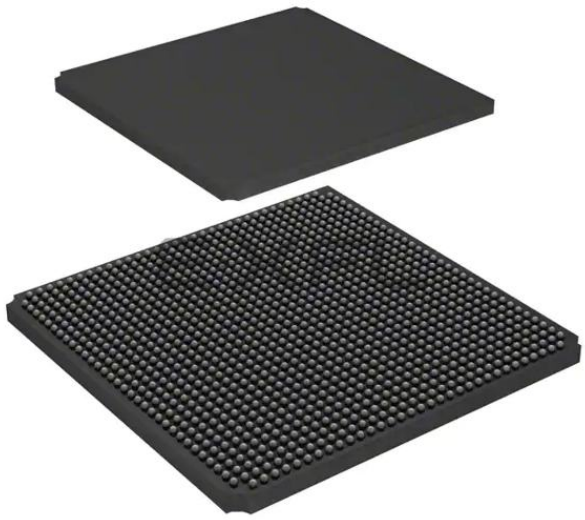
Lattice Semiconductor Corporation - LFE2M70SE-6F1152C Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

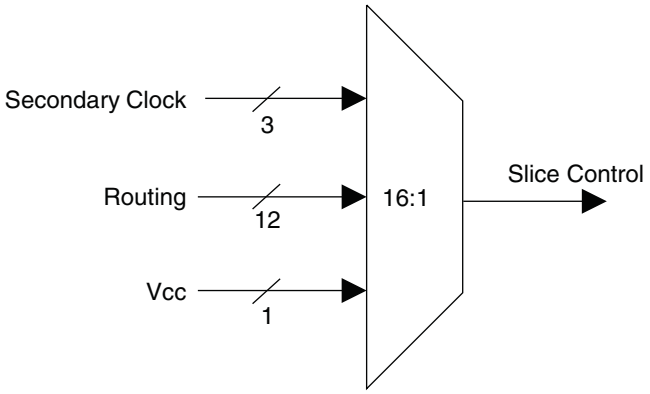
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	436
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-6f1152c

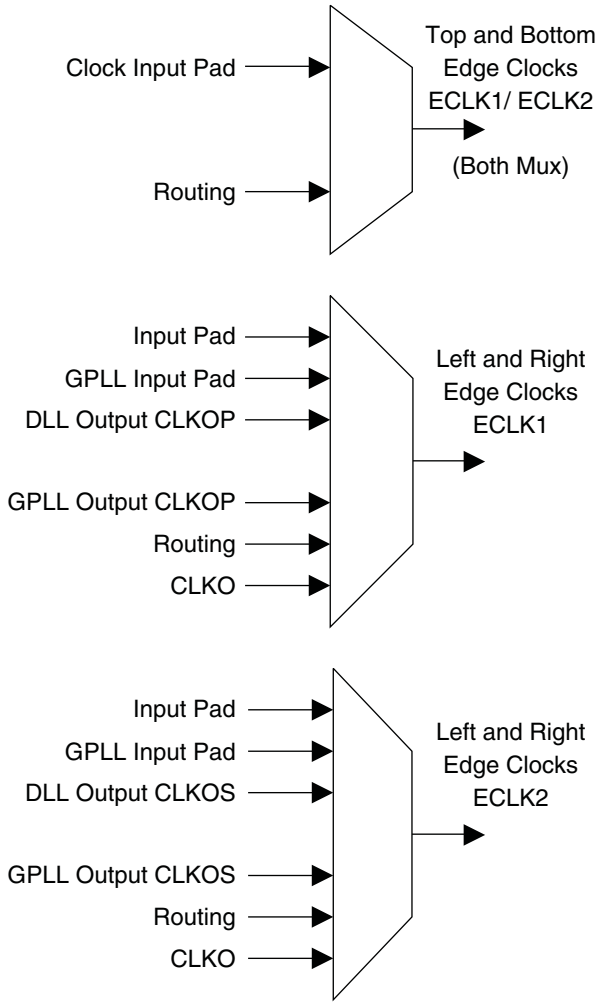
Figure 2-18. Slice0 through Slice2 Control Selection



Edge Clock Routing

LatticeECP2/M devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per device: two edge clocks per edge. Different PLL and DLL outputs are routed to the two muxes on the left and right sides of the device. In addition, the CLKO signal (generated from the DLLDELA block) is routed to all the edge clock muxes on the left and right sides of the device. Figure 2-19 shows the selection muxes for these clocks.

Figure 2-19. Edge Clock Mux Connections



sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

IPexpress™

The user can access the sysDSP block via the IPexpress tool, which provides the option to configure each DSP module (or group of modules) or by direct HDL instantiation. In addition, Lattice has partnered with The MathWorks® to support instantiation in the Simulink® tool, a graphical simulation environment. Simulink works with Diamond to dramatically shorten the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IP cores planned for the LatticeECP2/M DSP include the Bit Correlator, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/Decoder, Turbo Encoder/Decoder and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IP cores.

Resources Available in the LatticeECP2/M Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP2/M family. Table 2-10 shows the maximum available EBR RAM Blocks in each LatticeECP2/M device. EBR blocks, together with Distributed RAM can be used to store variables locally for fast DSP operations.

Table 2-9. Maximum Number of DSP Blocks in the LatticeECP2/M Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
ECP2-6	3	24	12	3
ECP2-12	6	48	24	6
ECP2-20	7	56	28	7
ECP2-35	8	64	32	8
ECP2-50	18	144	72	18
ECP2-70	22	176	88	22
ECP2M20	6	48	24	6
ECP2M35	8	64	32	8
ECP2M50	22	176	88	22
ECP2M70	24	192	96	24
ECP2M100	42	336	168	42

Table 2-10. Embedded SRAM in the LatticeECP2/M Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
ECP2-6	3	55
ECP2-12	12	221
ECP2-20	15	277
ECP2-35	18	332
ECP2-50	21	387
ECP2-70	60	1106
ECP2M20	66	1217
ECP2M35	114	2101
ECP2M50	225	4147
ECP2M70	246	4534
ECP2M100	288	5308

LatticeECP2/M Family Timing Adders[1, 2, 3] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
LVCMOS25_4mA	LVCMOS 2.5 4mA drive, slow slew rate	2.18	2.26	2.33	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive, slow slew rate	2.19	2.35	2.51	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive, slow slew rate	1.50	1.66	1.82	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive, slow slew rate	1.60	1.59	1.58	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive, slow slew rate	1.43	1.39	1.34	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive, slow slew rate	2.22	2.27	2.32	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive, slow slew rate	1.93	2.08	2.23	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive, slow slew rate	1.43	1.51	1.58	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive, slow slew rate	1.47	1.46	1.45	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive, slow slew rate	2.32	2.38	2.43	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive, slow slew rate	1.84	1.98	2.12	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive, slow slew rate	2.52	2.63	2.74	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive, slow slew rate	1.69	1.83	1.96	ns
PCI33	PCI33	0.04	0.04	0.04	ns

1. Timing Adders are characterized but not tested on every device.
2. LVCMOS timing measured with the load specified in Switching Test Condition table.
3. All other standards tested according to the appropriate specifications.
4. These timing adders are measured with the recommended resistor values.

Timing v.A 0.11

LatticeECP2 Pin Information Summary, LFE2-50 and LFE2-70 (Cont.)

Pin Type		LFE2-50		LFE2-70	
		484 fpBGA	672 fpBGA	672 fpBGA	900 fpBGA
Available DDR-Interfaces per I/O Bank[1]	Bank0	0	0	0	0
	Bank1	0	0	0	0
	Bank2	2	3	3	4
	Bank3	0	3	3	3
	Bank4	3	4	4	4
	Bank5	3	4	4	5
	Bank6	1	4	4	4
	Bank7	2	3	3	4
	Bank8	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0
	Bank1	0	0	0	0
	Bank2	0	0	0	0
	Bank3	0	0	0	0
	Bank4	46	62	62	72
	Bank5	46	68	68	80
	Bank6	0	0	0	0
	Bank7	0	0	0	0
	Bank8	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP (Cont.)

LFE2-6E/SE					LFE2-12E/12SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
91	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*
92	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*
93	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
94	VCC	-			VCC	-		
95	GND	-			GND	-		
96	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*
97	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*
98	PR16B	3	VREF2_3	C	PR16B	3	VREF2_3	C
99	PR16A	3	VREF1_3	T	PR16A	3	VREF1_3	T
100	PR15B	3	PCLKC3_0	C (LVDS)*	PR15B	3	PCLKC3_0	C (LVDS)*
101	PR15A	3	PCLKT3_0	T (LVDS)*	PR15A	3	PCLKT3_0	T (LVDS)*
102	VCC	-			VCC	-		
103	PR13B	2	PCLKC2_0/RDQ10	C	PR13B	2	PCLKC2_0/RDQ10	C
104	PR13A	2	PCLKT2_0/RDQ10	T	PR13A	2	PCLKT2_0/RDQ10	T
105	GND	-			GND	-		
106	VCCIO2	2			VCCIO2	2		
107	PR2B	2	VREF2_2	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*
108	PR2A	2	VREF1_2	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*
109	PT28B	1	VREF2_1	C	PT55B	1	VREF2_1	C
110	PT28A	1	VREF1_1	T	PT55A	1	VREF1_1	T
111	PT26B	1		C	PT54B	1		C
112	PT26A	1		T	PT54A	1		T
113	PT24B	1		C	PT52B	1		C
114	PT24A	1		T	PT52A	1		T
115	PT22B	1		C	PT50B	1		C
116	PT22A	1		T	PT50A	1		T
117	VCCIO1	1			VCCIO1	1		
118	PT20B	1		C	PT48B	1		C
119	PT20A	1		T	PT48A	1		T
120	GND	-			GND	-		
121	PT18B	1		C	PT44B	1		C
122	PT18A	1		T	PT44A	1		T
123	PT16A	1			PT40B	1		C
124	NC	1			PT40A	1		T
125	PT14B	1		C	PT34B	1		C
126	PT14A	1		T	PT34A	1		T
127	NC	1			NC	1		
128	VCC	-			VCC	-		
129	PT12B	1	PCLKC1_0	C	PT30B	1	PCLKC1_0	C
130	PT12A	1	PCLKT1_0	T	PT30A	1	PCLKT1_0	T
131	PT10B	0	PCLKC0_0	C	PT28B	0	PCLKC0_0	C
132	XRES	0			XRES	0		
133	GND	-			GND	-		
134	PT10A	0	PCLKT0_0	T	PT28A	0	PCLKT0_0	T
135	VCC	-			VCC	-		

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
R12	GND	-			GND	-		
R5	GND	-			GND	-		
T1	GND	-			GND	-		
T16	GND	-			GND	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
P5	P5	VCCIO5	5		
K5	K5	VCCIO6	6		
M3	M3	VCCIO6	6		
E3	E3	VCCIO7	7		
G5	G5	VCCIO7	7		
T15	T15	VCCIO8	8		
A1	A1	GND	-		
A16	A16	GND	-		
B12	B12	GND	-		
B5	B5	GND	-		
C8	C8	GND	-		
E15	E15	GND	-		
E2	E2	GND	-		
H14	H14	GND	-		
H8	H8	GND	-		
H9	H9	GND	-		
J3	J3	GND	-		
J8	J8	GND	-		
J9	J9	GND	-		
M15	M15	GND	-		
M2	M2	GND	-		
P9	P9	GND	-		
R12	R12	GND	-		
R5	R5	GND	-		
T1	T1	GND	-		
T16	T16	GND	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AB7	PB13B	5	BDQ15	C	PB22B	5	BDQ24	C
Y8	PB16A	5	BDQ15	T	PB25A	5	BDQ24	T
GNDIO	GNDIO5	-			GNDIO	-		
W9	PB15A	5	BDQS15	T	PB24A	5	BDQS24	T
AA8	PB16B	5	BDQ15	C	PB25B	5	BDQ24	C
V9	PB15B	5	BDQ15	C	PB24B	5	BDQ24	C
AB8	PB18A	5	BDQ15	T	PB27A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
W10	PB17A	5	BDQ15	T	PB26A	5	BDQ24	T
AA9	PB18B	5	BDQ15	C	PB27B	5	BDQ24	C
V10	PB17B	5	BDQ15	C	PB26B	5	BDQ24	C
GNDIO	GNDIO5	-			GNDIO	-		
Y10	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AB9	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
AA10	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AB10	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
AB11	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
U10	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AA11	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
U11	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
AB12	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
Y11	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
AA12	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
W11	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AB13	PB26A	5	PCLKT5_0/BDQ24	T	PB35A	5	PCLKT5_0/BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AB14	PB26B	5	PCLKC5_0/BDQ24	C	PB35B	5	PCLKC5_0/BDQ33	C
GNDIO	GNDIO5	-			GNDIO5	-		
Y12	PB32A	4	BDQ33	T	PB41A	4	BDQ42	T
W12	PB32B	4	BDQ33	C	PB41B	4	BDQ42	C
VCCIO	VCCIO4	4			VCCIO4	4		
U12	PB31A	4	PCLKT4_0/BDQ33	T	PB40A	4	PCLKT4_0/BDQ42	T
V12	PB31B	4	PCLKC4_0/BDQ33	C	PB40B	4	PCLKC4_0/BDQ42	C
U13	PB34A	4	BDQ33	T	PB43A	4	BDQ42	T
GNDIO	GNDIO4	-			GNDIO4	-		
AA13	PB33A	4	BDQS33	T	PB42A	4	BDQS42	T
U14	PB34B	4	BDQ33	C	PB43B	4	BDQ42	C
Y13	PB33B	4	BDQ33	C	PB42B	4	BDQ42	C
AB16	PB36A	4	BDQ33	T	PB45A	4	BDQ42	T
VCCIO	VCCIO4	4			VCCIO4	4		
AB15	PB35A	4	BDQ33	T	PB44A	4	BDQ42	T
AB17	PB36B	4	BDQ33	C	PB45B	4	BDQ42	C

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A2	GND	-			GND	-		
A25	GND	-			GND	-		
AA18	GND	-			GND	-		
AA24	GND	-			GND	-		
AA3	GND	-			GND	-		
AA9	GND	-			GND	-		
AD11	GND	-			GND	-		
AD16	GND	-			GND	-		
AD21	GND	-			GND	-		
AD6	GND	-			GND	-		
AE1	GND	-			GND	-		
AE26	GND	-			GND	-		
AF2	GND	-			GND	-		
AF25	GND	-			GND	-		
B1	GND	-			GND	-		
B26	GND	-			GND	-		
C11	GND	-			GND	-		
C16	GND	-			GND	-		
C21	GND	-			GND	-		
C6	GND	-			GND	-		
F18	GND	-			GND	-		
F24	GND	-			GND	-		
F3	GND	-			GND	-		
F9	GND	-			GND	-		
J13	GND	-			GND	-		
J14	GND	-			GND	-		
J21	GND	-			GND	-		
J6	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K13	GND	-			GND	-		
K14	GND	-			GND	-		
K16	GND	-			GND	-		
K17	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L16	GND	-			GND	-		
L17	GND	-			GND	-		
L24	GND	-			GND	-		
L3	GND	-			GND	-		
M13	GND	-			GND	-		
M14	GND	-			GND	-		
N10	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N14	GND	-			GND	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
K28	PR25A	2	RDQ29	T (LVDS)*
J24	PR24B	2	RDQ21	C
J26	PR24A	2	RDQ21	T
GND	GNDIO2	-		
K29	PR23B	2	RDQ21	C (LVDS)*
K30	PR23A	2	RDQ21	T (LVDS)*
J23	PR22B	2	RDQ21	C
J25	PR22A	2	RDQ21	T
VCCIO	VCCIO2	99		
J27	PR21B	2	RDQ21	C (LVDS)*
J28	PR21A	2	RDQS21	T (LVDS)*
H26	PR20B	2	RDQ21	C
GND	GNDIO2	-		
H24	PR20A	2	RDQ21	T
J29	PR19B	2	RDQ21	C (LVDS)*
J30	PR19A	2	RDQ21	T (LVDS)*
H25	PR18B	2	RDQ21	C
VCCIO	VCCIO2	2		
H23	PR18A	2	RDQ21	T
G27	PR15B	2	RUM1_SPLLC_FB_A/RDQ12	C
GND	GNDIO2	-		
H27	PR15A	2	RUM1_SPLLT_FB_A/RDQ12	T
G29	PR14B	2	RUM1_SPLLC_IN_A/RDQ12	C (LVDS)*
G28	PR14A	2	RUM1_SPLLT_IN_A/RDQ12	T (LVDS)*
VCCIO	VCCIO2	2		
GND	GNDIO2	-		
G26	PR6B	2		C (LVDS)*
G25	PR6A	2		T (LVDS)*
G30	PR5B	2		C
F30	PR5A	2		T
VCCIO	VCCIO2	2		
F26	PR4B	2		C (LVDS)*
F27	PR4A	2		T (LVDS)*
F29	PR3B	2		C
GND	GNDIO2	-		
F28	PR3A	2		T
H29	PR2B	2	VREF2_2	C (LVDS)*
H30	PR2A	2	VREF1_2	T (LVDS)*
VCCIO	VCCIO2	2		
B26	PT100B	1	VREF2_1	C
A26	PT100A	1	VREF1_1	T
GND	GNDIO1	-		
C25	PT99B	1		C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
G12	PT40B	0		C
E12	PT40A	0		T
VCCIO	VCCIO0	0		
B13	PT39B	0		C
A13	PT39A	0		T
H12	PT38B	0		C
F12	PT38A	0		T
C12	PT37B	0		C
GND	GNDIO0	-		
D12	PT37A	0		T
B12	PT36B	0		C
A12	PT36A	0		T
E11	PT35B	0		C
VCCIO	VCCIO0	0		
G11	PT35A	0		T
F11	PT34B	0		C
H11	PT34A	0		T
C11	PT33B	0		C
D11	PT33A	0		T
B11	PT32B	0		C
GND	GNDIO0	-		
A11	PT32A	0		T
E10	PT31B	0		C
VCCIO	VCCIO0	0		
G10	PT31A	0		T
F10	PT30B	0		C
H10	PT30A	0		T
D10	PT29B	0		C
C10	PT29A	0		T
GND	GNDIO0	-		
VCCIO	VCCIO0	0		
A7	PT16B	0		C
B7	PT16A	0		T
A6	PT15B	0		C
B6	PT15A	0		T
C7	PT14B	0		C
GND	GNDIO0	-		
D7	PT14A	0		T
D8	PT13B	0		C
VCCIO	VCCIO0	0		
E7	PT13A	0		T
C6	PT12B	0		C
D6	PT12A	0		T

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A3	GND	-			GND	-		
A9	GND	-			GND	-		
B12	GND	-			GND	-		
B6	GND	-			GND	-		
E15	GND	-			GND	-		
E2	GND	-			GND	-		
H14	GND	-			GND	-		
H8	GND	-			GND	-		
H9	GND	-			GND	-		
J3	GND	-			GND	-		
J8	GND	-			GND	-		
J9	GND	-			GND	-		
M15	GND	-			GND	-		
M2	GND	-			GND	-		
P9	GND	-			GND	-		
R12	GND	-			GND	-		
R5	GND	-			GND	-		
T1	GND	-			GND	-		
T16	GND	-			GND	-		
D10	NC	-			NC	-		
D11	NC	-			NC	-		
D12	NC	-			NC	-		
D13	NC	-			NC	-		
D14	NC	-			NC	-		
D4	NC	-			NC	-		
D5	NC	-			NC	-		
D6	NC	-			NC	-		
D7	NC	-			NC	-		
E11	NC	-			NC	-		
E6	NC	-			NC	-		
E8	NC	-			NC	-		
E9	NC	-			NC	-		
F10	NC	-			NC	-		
F7	NC	-			NC	-		
F8	NC	-			NC	-		
F9	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
C12	URC_SQ_VCCIB2	12		
B12	URC_SQ_HDINN2	12		C
C11	URC_SQ_VCCRX2	12		
A15	URC_SQ_HDOUTP2	12		T
C15	URC_SQ_VCCOB2	12		
B15	URC_SQ_HDOUTN2	12		C
C14	URC_SQ_VCCTX2	12		
B14	URC_SQ_HDOUTN3	12		C
A13	URC_SQ_VCCOB3	12		
A14	URC_SQ_HDOUTP3	12		T
C13	URC_SQ_VCCTX3	12		
B11	URC_SQ_HDINN3	12		C
B10	URC_SQ_VCCIB3	12		
A11	URC_SQ_HDINP3	12		T
C10	URC_SQ_VCCRX3	12		
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
E13	PT55B	1		C
D12	PT55A	1		T
GNDIO	GNDIO1	-		
A9	PT54B	1		C
A8	PT54A	1		T
A7	PT53B	1		C
A6	PT53A	1		T
VCCIO	VCCIO1	1		
E12	PT52B	1		C
F12	PT52A	1		T
A5	PT51B	1		C
A4	PT51A	1		T
GNDIO	GNDIO1	-		
B7	PT50B	1		C
B8	PT50A	1		T
G11	PT49B	1		C
E11	PT49A	1		T
VCCIO	VCCIO1	1		
D11	PT48B	1	VREF2_1	C
D10	PT48A	1	VREF1_1	T
G10	PT47B	1	PCLKC1_0	C
F11	PT47A	1	PCLKT1_0	T
G9	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
F9	PT46A	0	PCLKT0_0	T
C9	PT45B	0	VREF2_0	C

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C15	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B15	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C14	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A18	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C18	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B18	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C17	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B17	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A16	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A17	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C16	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B14	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B13	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A14	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C13	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
-	-	-			GNDIO1	-		
-	-	-			VCCIO1	1		
E17	PT46B	1		C	PT55B	1		C
D17	PT46A	1		T	PT55A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
F17	PT45B	1		C	PT54B	1		C
D16	PT45A	1		T	PT54A	1		T
F19	PT44B	1		C	PT53B	1		C
F18	PT44A	1		T	PT53A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
E16	PT43B	1		C	PT52B	1		C
D15	PT43A	1		T	PT52A	1		T
G18	PT42B	1		C	PT51B	1		C
E15	PT42A	1		T	PT51A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
G17	PT41B	1		C	PT50B	1		C
E14	PT41A	1		T	PT50A	1		T
D14	PT40B	1		C	PT49B	1		C
D13	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
F15	PT39B	1	VREF2_1	C	PT48B	1	VREF2_1	C
E12	PT39A	1	VREF1_1	T	PT48A	1	VREF1_1	T
H17	PT38B	1	PCLKC1_0	C	PT47B	1	PCLKC1_0	C
E13	PT38A	1	PCLKT1_0	T	PT47A	1	PCLKT1_0	T
C12	PT37B	0	PCLKC0_0	C	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT37A	0	PCLKT0_0	T	PT46A	0	PCLKT0_0	T
C11	PT36B	0	VREF2_0	C	PT45B	0	VREF2_0	C
F14	PT36A	0	VREF1_0	T	PT45A	0	VREF1_0	T

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D23	NC	-			NC	-		
D24	NC	-			NC	-		
D25	NC	-			NC	-		
D26	NC	-			NC	-		
E20	NC	-			NC	-		
E21	NC	-			NC	-		
E25	NC	-			NC	-		
E26	NC	-			NC	-		
F20	NC	-			NC	-		
G20	NC	-			NC	-		
K10	NC	-			NC	-		
K17	NC	-			NC	-		
R4	NC	-			NC	-		
U10	NC	-			NC	-		
U23	NC	-			NC	-		
V10	NC	-			NC	-		
W7	NC	-			NC	-		
AB21	PB69B	4	BDQ69	C	NC	-		
AC20	PB58A	4	BDQ60	T	NC	-		
AC21	PB63A	4	BDQ60	T	NC	-		
AC22	PB69A	4	BDQS69****	T	NC	-		
AC23	PB71A	4	BDQ69	T	NC	-		
AC25	PB71B	4	BDQ69	C	NC	-		
AD26	PB70B	4	BDQ69	C	NC	-		
W20	PB72B	4	BDQ69	C	NC	-		
H7	L_VCCPLL	-			L_VCCPLL	-		
K6	L_VCCPLL	-			L_VCCPLL	-		
P7	L_VCCPLL	-			L_VCCPLL	-		
R8	L_VCCPLL	-			L_VCCPLL	-		
V18	R_VCCPLL	-			R_VCCPLL	-		
P20	R_VCCPLL	-			R_VCCPLL	-		
J17	R_VCCPLL	-			R_VCCPLL	-		
G19	R_VCCPLL	-			R_VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
Y22	PR60B	3		C	PR81B	3	RDQ82	C
Y23	PR60A	3		T	PR81A	3	RDQ82	T
AB26	NC	-			PR80B	3	RDQ82	C (LVDS)*
AB27	NC	-			PR80A	3	RDQ82	T (LVDS)*
-	-	-			VCCIO3	3		
Y24	NC	-			PR79B	3	RDQ82	C
Y25	NC	-			PR79A	3	RDQ82	T
AA29	NC	-			PR78B	3	RDQ82	C (LVDS)*
Y28	NC	-			PR78A	3	RDQ82	T (LVDS)*
Y30	NC	-			PR76B	3	RDQ73	C
Y29	NC	-			PR76A	3	RDQ73	T
-	-	-			GNDIO3	-		
-	-	-			-	-		
W22	NC	-			PR75B	3	RDQ73	C (LVDS)*
V22	NC	-			PR75A	3	RDQ73	T (LVDS)*
Y27	NC	-			PR74B	3	RDQ73	C
-	-	-			VCCIO3	3		
Y26	NC	-			PR74A	3	RDQ73	T
W30	NC	-			PR73B	3	RDQ73	C (LVDS)*
W29	NC	-			PR73A	3	RDQS73	T (LVDS)*
-	-	-			GNDIO3	-		
W25	NC	-			PR72B	3	RDQ73	C
W26	NC	-			PR72A	3	RDQ73	T
U29	PR59B	3		C (LVDS)*	PR71B	3	RDQ73	C (LVDS)*
V29	PR59A	3		T (LVDS)*	PR71A	3	RDQ73	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
V30	PR58B	3		C	PR70B	3	RDQ73	C
U30	PR58A	3		T	PR70A	3	RDQ73	T
W27	PR57B	3		C (LVDS)*	PR69B	3	RDQ73	C (LVDS)*
W28	PR57A	3		T (LVDS)*	PR69A	3	RDQ73	T (LVDS)*
V24	PR55B	3	RDQ52	C	PR67B	3	RDQ64	C
V25	PR55A	3	RDQ52	T	PR67A	3	RDQ64	T
GNDIO	GNDIO3	-			GNDIO3	-		
U28	PR54B	3	RDQ52	C (LVDS)*	PR66B	3	RDQ64	C (LVDS)*
U27	PR54A	3	RDQ52	T (LVDS)*	PR66A	3	RDQ64	T (LVDS)*
U23	PR53B	3	RDQ52	C	PR65B	3	RDQ64	C
V23	PR53A	3	RDQ52	T	PR65A	3	RDQ64	T
VCCIO	VCCIO3	3			VCCIO3	3		
V26	PR52B	3	RDQ52	C (LVDS)*	PR64B	3	RDQ64	C (LVDS)*
U26	PR52A	3	RDQS52	T (LVDS)*	PR64A	3	RDQS64	T (LVDS)*
U25	PR51B	3	RDQ52	C	PR63B	3	RDQ64	C
GNDIO	GNDIO3	-			GNDIO3	-		
U24	PR51A	3	RDQ52	T	PR63A	3	RDQ64	T
T30	PR50B	3	RDQ52	C (LVDS)*	PR62B	3	RDQ64	C (LVDS)*
R30	PR50A	3	RDQ52	T (LVDS)*	PR62A	3	RDQ64	T (LVDS)*
T23	PR49B	3	RDQ52	C	PR61B	3	RDQ64	C
VCCIO	VCCIO3	3			VCCIO3	3		
T22	PR49A	3	RDQ52	T	PR61A	3	RDQ64	T

LatticeECP2M Part Number Description

LFE2M XXX XE – X XXXXXX X

Device Family
ECP2M (LatticeECP2 FPGA + SERDES)

Logic Capacity
20 = 20K LUTs
35 = 35K LUTs
50 = 50K LUTs
70 = 70K LUTs
100 = 100K LUTs

Encryption
S = Security Series (Encryption Feature)
Blank = Standard Series (No Encryption)

Supply Voltage
E = 1.2V

Grade
C = Commercial
I = Industrial

Package
F256 = 256-ball fpBGA
F484 = 484-ball fpBGA
F672 = 672-ball fpBGA
F900 = 900-ball fpBGA
F1152 = 1152-ball fpBGA

FN256 = 256-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA
FN672 = 672-ball Lead-free fpBGA
FN900 = 900-ball Lead-free fpBGA
FN1152 = 1152-ball Lead-free fpBGA

Speed
5 = Slowest
6
7 = Fastest

Ordering Information

Note:þLatticeECP2M devices are dual marked. For example, the commercial speed grade LFE2M50E-7F672C is also marked with industrial grade -6I (LFE2M50E-6F672I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial grade does not have industrial markings. The markings appear as follows:

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5F1152C	436	1.2V	-5	fpBGA	1152	Com	70
LFE2M70SE-6F1152C	436	1.2V	-6	fpBGA	1152	Com	70
LFE2M70SE-7F1152C	436	1.2V	-7	fpBGA	1152	Com	70
LFE2M70SE-5F900C	416	1.2V	-5	fpBGA	900	Com	70
LFE2M70SE-6F900C	416	1.2V	-6	fpBGA	900	Com	70
LFE2M70SE-7F900C	416	1.2V	-7	fpBGA	900	Com	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5F1152C	520	1.2V	-5	fpBGA	1152	Com	100
LFE2M100SE-6F1152C	520	1.2V	-6	fpBGA	1152	Com	100
LFE2M100SE-7F1152C	520	1.2V	-7	fpBGA	1152	Com	100
LFE2M100SE-5F900C	416	1.2V	-5	fpBGA	900	Com	100
LFE2M100SE-6F900C	416	1.2V	-6	fpBGA	900	Com	100
LFE2M100SE-7F900C	416	1.2V	-7	fpBGA	900	Com	100

LatticeECP2/M Family Data Sheet Supplemental Information

July 2012 **Data Sheet DS1006**

For Further Information

A variety of technical notes for the LatticeECP2/M family are available on the Lattice web site at www.latticesemi.com.

- TN1102, LatticeECP2/M sysIO Usage Guide
- TN1103, LatticeECP2/M sysCLOCK PLL Design and Usage Guide
- TN1104, LatticeECP2/M Memory Usage Guide
- TN1105, LatticeECP2/M High-Speed I/O Interface
- TN1106, Power Estimation and Management for LatticeECP2/M Devices
- TN1107, LatticeECP2/M sysDSP Usage Guide
- TN1108, LatticeECP2/M sysCONFIG Usage Guide
- TN1109, LatticeECP2/M Configuration Encryption Usage Guide
- TN1113, LatticeECP2/M Soft Error Detection (SED) Usage Guide
- TN1124, LatticeECP2M SERDES/PCS Usage Guide
- TN1162, LatticeECP2/M Hardware Checklist

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com

© 2012 Lattice Semiconductor Corp. All Lattice trademarks, registered trademarks, patents, and disclaimers are as listed at www.latticesemi.com/legal. All other brand or product names are trademarks or registered trademarks of their respective holders. The specifications and information herein are subject to change without notice.